



## Material Content Data Sheet



<b>Sales Product Name</b>		BSO203SP H		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA000719922						
<b>Package</b>		PG-DSO-8-39		<b>Weight*</b>		83.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.664	1.99	1.99	19905	19905
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		123	
	non noble metal	zinc	7440-66-6	0.041	0.05		490	
	non noble metal	iron	7439-89-6	0.820	0.98		9805	
wire	non noble metal	copper	7440-50-8	33.276	39.81	40.85	398139	408557
	non noble metal	copper	7440-50-8	0.139	0.17	0.17	1659	1659
	encapsulation	organic material	carbon black	1333-86-4	0.231	0.28		2763
	plastics	epoxy resin	-	7.160	8.57		85666	
	inorganic material	silicondioxide	60676-86-0	38.802	46.42	55.27	464254	552683
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9737	9737
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	868	868
glue	plastics	epoxy resin	-	0.083	0.10		989	
	noble metal	silver	7440-22-4	0.468	0.56	0.66	5602	6591
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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